

*MEMORY Mobile FCRAM™*

CMOS

**16M Bit (1 M word x 16 bit)***Mobile Phone Application Specific Memory***MB82DS01181E-70L-A****CMOS 1,048,576-WORD x 16 BIT  
Fast Cycle Random Access Memory  
with Low Power SRAM Interface****■ DESCRIPTION**

The Fujitsu MB82DS01181E is a CMOS Fast Cycle Random Access Memory (FCRAM) with asynchronous Static Random Access Memory (SRAM) interface containing 16,777,216 storages accessible in a 16-bit format. This MB82DS01181E is suited for mobile applications such as Cellular Handset and PDA.

**■ FEATURES**

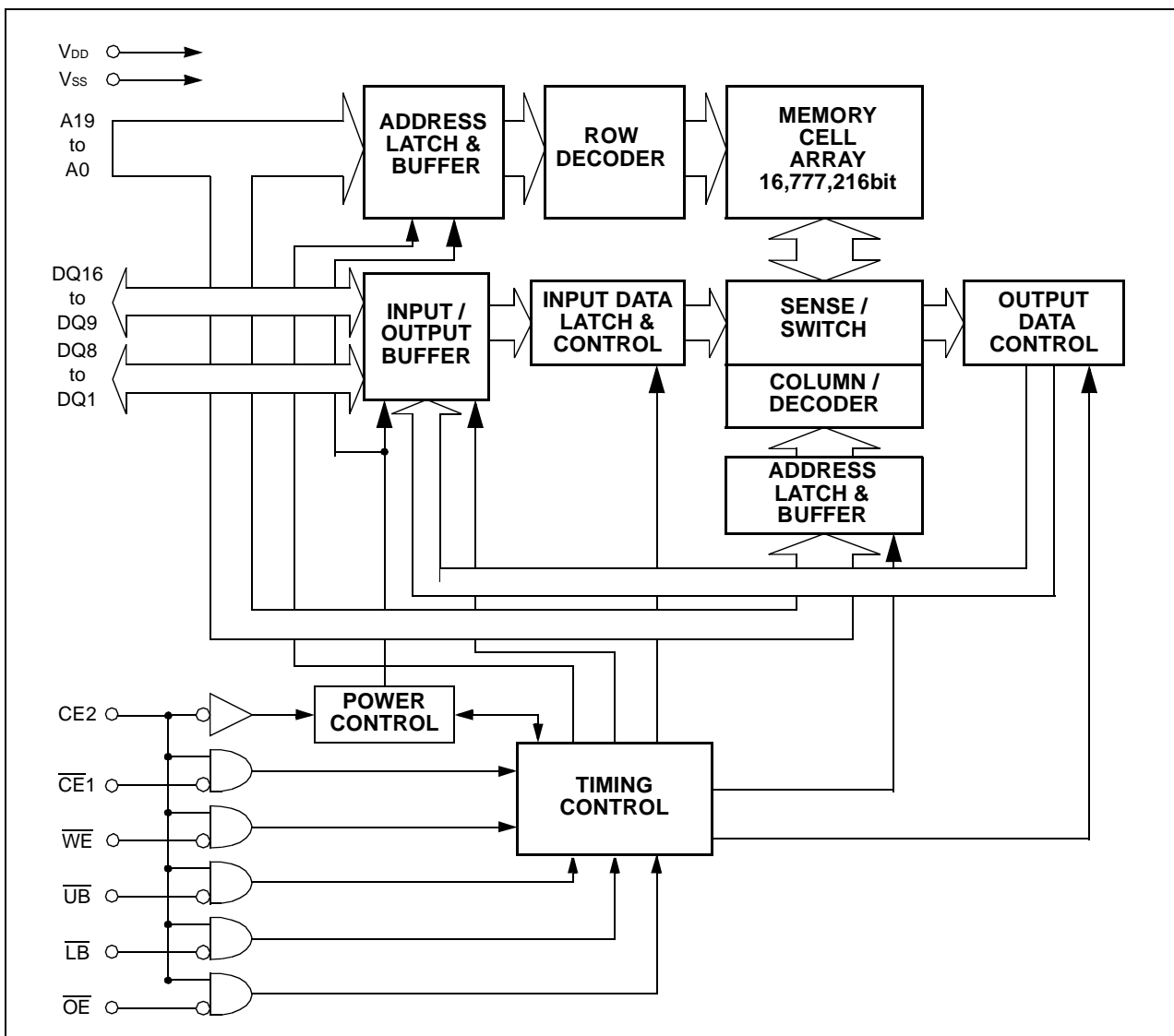
- Asynchronous SRAM Interface
- Fast Random Access Time  
 $t_{CE} = 70\text{ns} (-70)$
- Low Voltage Operating Condition  
 $V_{DD} = +1.7\text{V to } +1.95\text{V}$
- Wide Operating Temperature  
 $T_A = -30^\circ\text{C to } +85^\circ\text{C}$
- Byte Control by  $\overline{LB}$  and  $\overline{UB}$
- Low Power Consumption  
 $I_{DDA1} = 20\text{mA max}$   
 $I_{DDs1} = 100\mu\text{A max}$
- Power Down mode

# MB82DS01181E -70L-A

## ■ PIN DESCRIPTION

Pin Name	Description
A <sub>19</sub> to A <sub>0</sub>	Address Input
$\overline{\text{CE}}1$	Chip Enable (Low Active)
CE2	Chip Enable (High Active)
$\overline{\text{WE}}$	Write Enable (Low Active)
$\overline{\text{OE}}$	Output Enable (Low Active)
$\overline{\text{UB}}$	Upper Byte Control (Low Active)
$\overline{\text{LB}}$	Lower Byte Control (Low Active)
DQ <sub>16-9</sub>	Upper Byte Data Input/Output
DQ <sub>8-1</sub>	Lower Byte Data Input/Output
V <sub>DD</sub>	Power Supply
V <sub>SS</sub>	Ground

## ■ BLOCK DIAGRAM



■ FUNCTION TRUTH TABLE

Mode	Note	CE2	$\overline{CE1}$	$\overline{WE}$	$\overline{OE}$	$\overline{LB}$	$\overline{UB}$	A19-0	DQ8-1	DQ16-9	I <sub>DD</sub>	Data Retention
Standby (Deselect)		H	H	X	X	X	X	X	High-Z	High-Z	I <sub>DDs</sub>	Yes
Output Disable	*1	H	L	H	H	X	X	*3	High-Z	High-Z	I <sub>DDA</sub>	
Output Disable (No Read)				H	L	H	H	Valid	High-Z	High-Z		
Read (Upper Byte)						H	L	Valid	High-Z	Output Valid		
Read (Lower Byte)						L	H	Valid	Output Valid	High-Z		
Read (Word)						L	L	Valid	Output Valid	Output Valid		
No Write				L	H	H	H	Valid	Invalid	Invalid		
Write (Upper Byte)						H	L	Valid	Invalid	Input Valid		
Write (Lower Byte)						L	H	Valid	Input Valid	Invalid		
Write (Word)						L	L	Valid	Input Valid	Input Valid		
Power Down	*2			L	X	X	X	X	X	X		High-Z

**Notes** L = V<sub>IL</sub>, H = V<sub>IH</sub>, X can be either V<sub>IL</sub> or V<sub>IH</sub>, High-Z = High Impedance

\*1: Should not be kept this logic condition longer than 1μs.

Please contact local FUJITSU representative for the relaxation of 1μs limitation.

\*2: Power Down mode can be entered from Standby state and all DQ pins are in High-Z state.

\*3: Can be either V<sub>IL</sub> or V<sub>IH</sub> but must be valid before Read or Write.

# MB82DS01181E -70L-A

## ■ ABSOLUTE MAXIMUM RATINGS

(See WARNING below.)

Parameter	Symbol	Value	Unit
Voltage of V <sub>DD</sub> Supply Relative to V <sub>SS</sub>	V <sub>DD</sub>	-0.5 to +3.6	V
Voltage at Any Pin Relative to V <sub>SS</sub>	V <sub>IN</sub> , V <sub>OUT</sub>	-0.5 to +3.6	V
Short Circuit Output Current	I <sub>OUT</sub>	±50	mA
Storage Temperature	T <sub>STG</sub>	-55 to +125	°C

**WARNING:** Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

## ■ RECOMMENDED OPERATING CONDITIONS

(See WARNING below.)

Parameter	Notes	Symbol	Min.	Max.	Unit
Supply Voltage		V <sub>DD</sub>	1.7	1.95	V
		V <sub>SS</sub>	0	0	V
High Level Input Voltage	*1	V <sub>IH</sub>	V <sub>DD</sub> *0.8	V <sub>DD</sub> +0.2	V
Low Level Input Voltage	*2	V <sub>IL</sub>	-0.3	V <sub>DD</sub> *0.2	V
Ambient Temperature		T <sub>A</sub>	-30	85	°C

(Referenced to V<sub>SS</sub>)

**Notes** \*1: Maximum DC voltage on input and I/O pins are V<sub>DD</sub>+0.2V. During voltage transitions, inputs may positive overshoot to V<sub>DD</sub>+1.0V for periods of up to 5 ns.

\*2: Minimum DC voltage on input or I/O pins are -0.3V. During voltage transitions, inputs may negative overshoot V<sub>SS</sub> to -1.0V for periods of up to 5ns.

**WARNING:** Recommended operating conditions are normal operating ranges for the semiconductor device. All the device's electrical characteristics are warranted when operated within these ranges.

Always use semiconductor devices within the recommended operating conditions. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representative beforehand.

## ■ PACKAGE PIN CAPACITANCE

Test conditions: T<sub>A</sub> = 25°C, f = 1.0 MHz

Symbol	Description	Test Setup	Typ.	Max.	Unit
C <sub>IN1</sub>	Address Input Capacitance	V <sub>IN</sub> = 0V	—	5	pF
C <sub>IN2</sub>	Control Input Capacitance	V <sub>IN</sub> = 0V	—	5	pF
C <sub>IO</sub>	Data Input/Output Capacitance	V <sub>IO</sub> = 0V	—	8	pF

**■ DC CHARACTERISTICS**

(Under Recommended Operating Conditions unless otherwise noted)Note \*1,\*2,\*3

Parameter	Symbol	Test Conditions	Min.	Max.	Unit	
Input Leakage Current	$I_{LI}$	$V_{IN} = V_{SS}$ to $V_{DD}$	-1.0	+1.0	$\mu A$	
Output Leakage Current	$I_{LO}$	$V_{OUT} = V_{SS}$ to $V_{DD}$ , Output Disable	-1.0	+1.0	$\mu A$	
Output High Voltage Level	$V_{OH}$	$V_{DD} = V_{DD}(\min)$ , $I_{OH} = -0.5mA$	1.4	—	V	
Output Low Voltage Level	$V_{OL}$	$I_{OL} = 1mA$	—	0.4	V	
$V_{DD}$ Power Down Current	$I_{DDPS}$	$V_{DD} = V_{DD} \max.$ , $V_{IN} = V_{IH}$ or $V_{IL}$ , $CE2 \leq 0.2V$	—	10	$\mu A$	
$V_{DD}$ Standby Current	$I_{DDS}$	$V_{DD} = V_{DD} \max.$ , $V_{IN} = V_{IH}$ or $V_{IL}$ , $CE1 = CE2 = V_{IH}$	—	1	mA	
	$I_{DDS1}$	$V_{DD} = V_{DD} \max.$ , $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{DD} - 0.2V$ , $CE1 = CE2 \geq V_{DD} - 0.2V$	—	100	$\mu A$	
$V_{DD}$ Active Current	$I_{DDA1}$	$V_{DD} = V_{DD} \max.$ , $V_{IN} = V_{IH}$ or $V_{IL}$ , $CE1 = V_{IL}$ and $CE2 = V_{IH}$ ,	$t_{RC} / t_{WC} =$ minimum	—	20	mA
	$I_{DDA2}$	$I_{OUT} = 0mA$	$t_{RC} / t_{WC} =$ 1 $\mu s$	—	3	mA

**Notes** \*1: All voltages are referenced to  $V_{SS}$ .

\*2: DC Characteristics are measured after following POWER-UP timing.

 \*3:  $I_{OUT}$  depends on the output load conditions.

## ■ AC CHARACTERISTICS

(Under Recommended Operating Conditions unless otherwise noted)

### READ OPERATION

Parameter	Symbol	Value		Unit	Notes
		Min.	Max.		
Read Cycle Time	$t_{RC}$	80	1000	ns	*1, *2
$\overline{CE1}$ Access Time	$t_{CE}$	—	70	ns	*3
$\overline{OE}$ Access Time	$t_{OE}$	—	45	ns	*3
Address Access Time	$t_{AA}$	—	70	ns	*3, *5
$\overline{LB} / \overline{UB}$ Access Time	$t_{BA}$	—	30	ns	*3
Output Data Hold Time	$t_{OH}$	5	—	ns	*3
$\overline{CE1}$ Low to Output Low-Z	$t_{CLZ}$	5	—	ns	*4
$\overline{OE}$ Low to Output Low-Z	$t_{OLZ}$	0	—	ns	*4
$\overline{LB} / \overline{UB}$ Low to Output Low-Z	$t_{BLZ}$	0	—	ns	*4
$\overline{CE1}$ High to Output High-Z	$t_{CHZ}$	—	20	ns	*3
$\overline{OE}$ High to Output High-Z	$t_{OHZ}$	—	20	ns	*3
$\overline{LB} / \overline{UB}$ High to Output High-Z	$t_{BHZ}$	—	20	ns	*3
Address Setup Time to $\overline{CE1}$ Low	$t_{ASC}$	-5	—	ns	
Address Setup Time to $\overline{OE}$ Low	$t_{ASO}$	10	—	ns	
Address Invalid Time	$t_{AX}$	—	10	ns	*5
Address Hold Time from $\overline{CE1}$ High	$t_{CHAH}$	-5	—	ns	*6
Address Hold Time from $\overline{OE}$ High	$t_{OHAH}$	-5	—	ns	
$\overline{WE}$ High to $\overline{OE}$ Low Time for Read	$t_{WHOL}$	15	1000	ns	*7
$\overline{CE1}$ High Pulse Width	$t_{CP}$	15	—	ns	

**Notes** \*1: Maximum value is applicable if  $\overline{CE1}$  is kept at Low without any address change. If the relaxation is needed by system operation, please contact local FUJITSU representative for the relaxation of 1 $\mu$ s limitation.

\*2: Address should not be changed within minimum  $t_{RC}$ .

\*3: The output load 50pF with 50ohm termination to  $V_{DD} \cdot 0.5$  V.

\*4: The output load 5pF without any other load.

\*5: Applicable when  $\overline{CE1}$  is kept at Low.

\*6:  $t_{RC}(\text{min})$  must be satisfied.

\*7: If actual value of  $t_{WHOL}$  is shorter than specified minimum values, the actual  $t_{AA}$  of following Read may become longer by the amount of subtracting actual value from specified minimum value.

■ AC CHARACTERISTICS (Continued)

WRITE OPERATION

Parameter	Symbol	Value		Unit	Notes
		Min.	Max.		
Write Cycle Time	$t_{WC}$	80	1000	ns	*1, *2
Address Setup Time	$t_{AS}$	0	—	ns	*2
$\overline{CE1}$ Write Pulse Width	$t_{CW}$	45	—	ns	*3
$\overline{WE}$ Write Pulse Width	$t_{WP}$	45	—	ns	*3
$\overline{LB} / \overline{UB}$ Write Pulse Width	$t_{BW}$	45	—	ns	*3
$\overline{LB} / \overline{UB}$ Byte Mask Setup Time	$t_{BS}$	-5	—	ns	*4
$\overline{LB} / \overline{UB}$ Byte Mask Hold Time	$t_{BH}$	-5	—	ns	*5
Write Recovery Time	$t_{WR}$	0	—	ns	*6
$\overline{CE1}$ High Pulse Width	$t_{CP}$	15	—	ns	
$\overline{WE}$ High Pulse Width	$t_{WHP}$	15	1000	ns	
$\overline{LB} / \overline{UB}$ High Pulse Width	$t_{BHP}$	15	1000	ns	
Data Setup Time	$t_{DS}$	20	—	ns	
Data Hold Time	$t_{DH}$	0	—	ns	
$\overline{OE}$ High to $\overline{CE1}$ Low Setup Time for Write	$t_{OHCL}$	-5	—	ns	*7
$\overline{OE}$ High to Address Setup Time for Write	$t_{OES}$	0	—	ns	*8
$\overline{LB}$ and $\overline{UB}$ Write Pulse Overlap	$t_{BWO}$	20	—	ns	

- Notes**
- \*1: Maximum value is applicable if  $\overline{CE1}$  is kept at Low without any address change. If the relaxation is needed by system operation, please contact local FUJITSU representative for the relaxation of 1 $\mu$ s limitation.
  - \*2: Minimum value must be equal or greater than the sum of write pulse ( $t_{CW}$ ,  $t_{WP}$  or  $t_{BW}$ ) and write recovery time ( $t_{WRC}$ ,  $t_{WR}$  or  $t_{BR}$ ).
  - \*3: Write pulse is defined from High to Low transition of  $\overline{CE1}$ ,  $\overline{WE}$ , or  $\overline{LB} / \overline{UB}$ , whichever occurs last.
  - \*4: Applicable for byte mask only. Byte mask setup time is defined to the High to Low transition of  $\overline{CE1}$  or  $\overline{WE}$  whichever occurs last.
  - \*5: Applicable for byte mask only. Byte mask hold time is defined from the Low to High transition of  $\overline{CE1}$  or  $\overline{WE}$  whichever occurs first.
  - \*6: Write recovery is defined from Low to High transition of  $\overline{CE1}$ ,  $\overline{WE}$ , or  $\overline{LB} / \overline{UB}$ , whichever occurs first.
  - \*7: If  $\overline{OE}$  is Low after minimum  $t_{OHCL}$ , read cycle is initiated. In other word,  $\overline{OE}$  must be brought to High within 5ns after  $\overline{CE1}$  is brought to Low. Once read cycle is initiated, new write pulse should be input after minimum  $t_{RC}$  is met.
  - \*8: If  $\overline{OE}$  is Low after new address input, read cycle is initiated. In other word,  $\overline{OE}$  must be brought to High at the same time or before new address valid. Once read cycle is initiated, new write pulse should be input after minimum  $t_{RC}$  is met.

## ■ AC CHARACTERISTICS (Continued)

### POWER DOWN PARAMETERS

Parameter	Symbol	Value		Unit	Note
		Min.	Max.		
CE2 Low Setup Time for Power Down Entry	t <sub>CSP</sub>	10	—	ns	
CE2 Low Hold Time after Power Down Entry	t <sub>C2LP</sub>	80	—	ns	
$\overline{CE1}$ High Hold Time following CE2 High after Power Down Exit [SLEEP mode only]	t <sub>CHH</sub>	300	—	μs	*1
$\overline{CE1}$ High Setup Time following CE2 High after Power Down Exit	t <sub>CHS</sub>	0	—	ns	

**Notes** \*1: Applicable also to power-up.

### OTHER TIMING PARAMETERS

Parameter	Symbol	Value		Unit	Note
		Min.	Max.		
$\overline{CE1}$ High to $\overline{OE}$ Invalid Time for Standby Entry	t <sub>CHOX</sub>	10	—	ns	
$\overline{CE1}$ High to $\overline{WE}$ Invalid Time for Standby Entry	t <sub>CHWX</sub>	10	—	ns	*1
$\overline{CE1}$ High Hold Time following CE2 High after Power-up	t <sub>CHH</sub>	300	—	μs	
Input Transition Time	t <sub>T</sub>	1	25	ns	*2

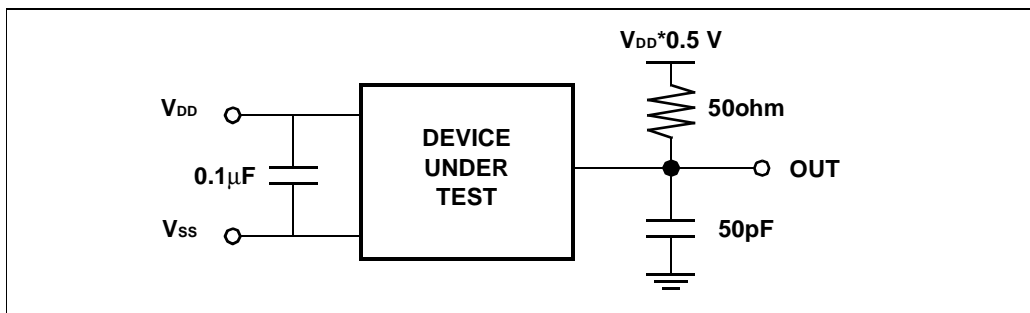
**Notes** \*1: Some data might be written into any address location if t<sub>CHWX</sub>(min) is not satisfied.

\*2: The Input Transition Time (t<sub>T</sub>) at AC testing is 5ns as shown in below. If actual t<sub>T</sub> is longer than 5ns, it may violate AC specification of some timing parameters.

### AC TEST CONDITIONS

Symbol	Description	Test Setup	Value	Unit	Note
V <sub>IH</sub>	Input High Level		V <sub>DD</sub> * 0.8	V	
V <sub>IL</sub>	Input Low Level		V <sub>DD</sub> * 0.2	V	
V <sub>REF</sub>	Input Timing Measurement Level		V <sub>DD</sub> * 0.5	V	
t <sub>T</sub>	Input Transition Time	Between V <sub>IL</sub> and V <sub>IH</sub>	5	ns	

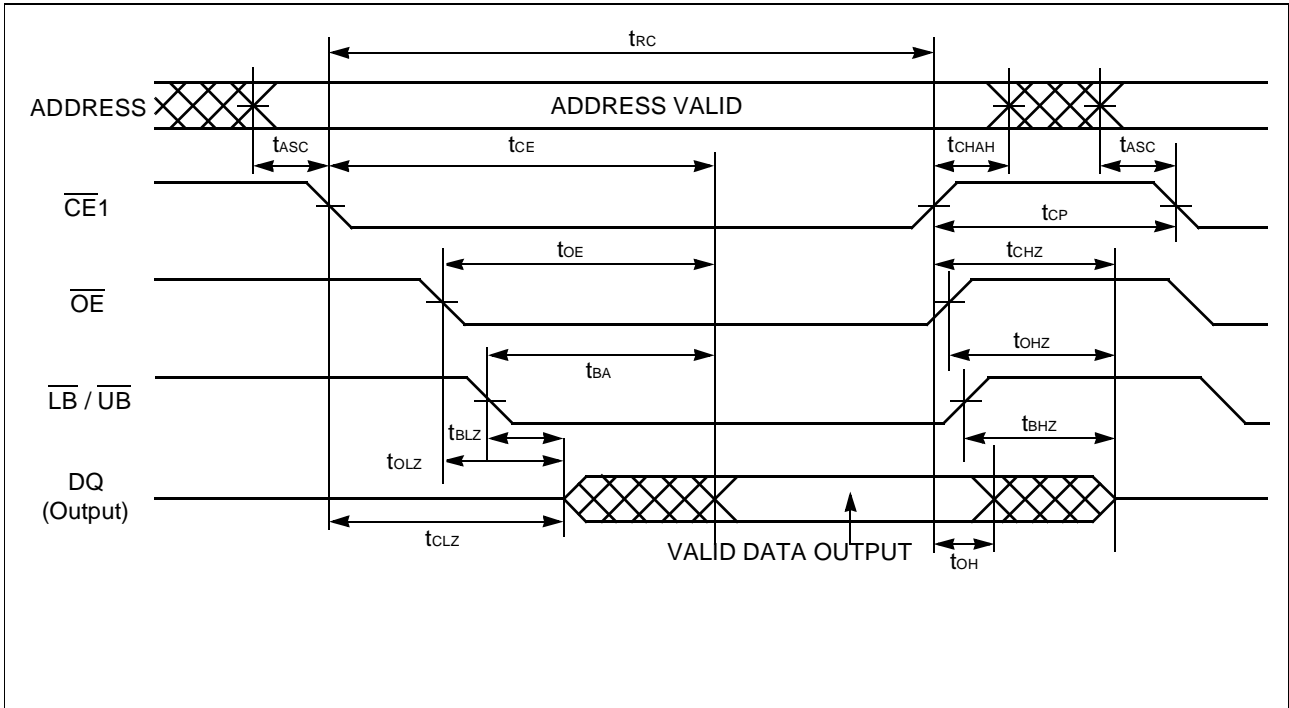
### AC MEASUREMENT OUTPUT LOAD CIRCUIT



■ TIMING DIAGRAMS

READ Timing #1 (Basic Timing)

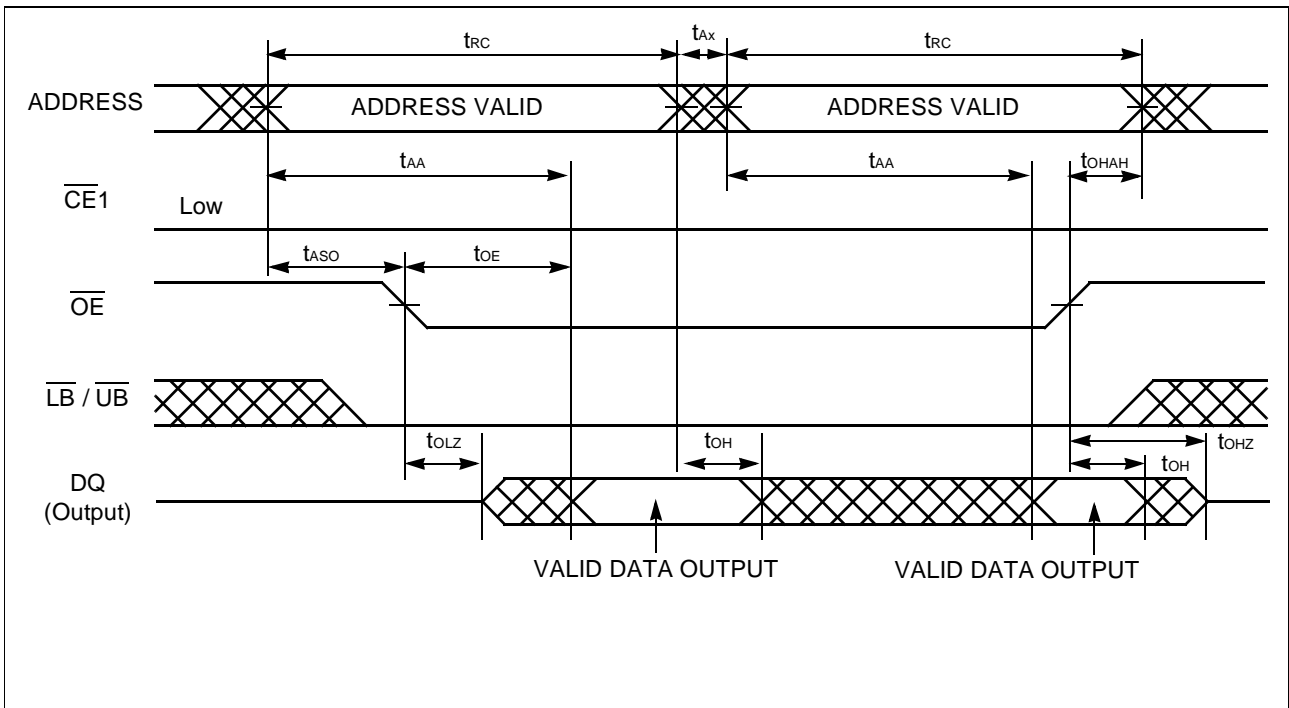
See Note.



**Note:** This timing diagram assumes  $CE2=H$  and  $\overline{WE}=H$ .

READ Timing #2 ( $\overline{OE}$  & Address Access)

See Note.

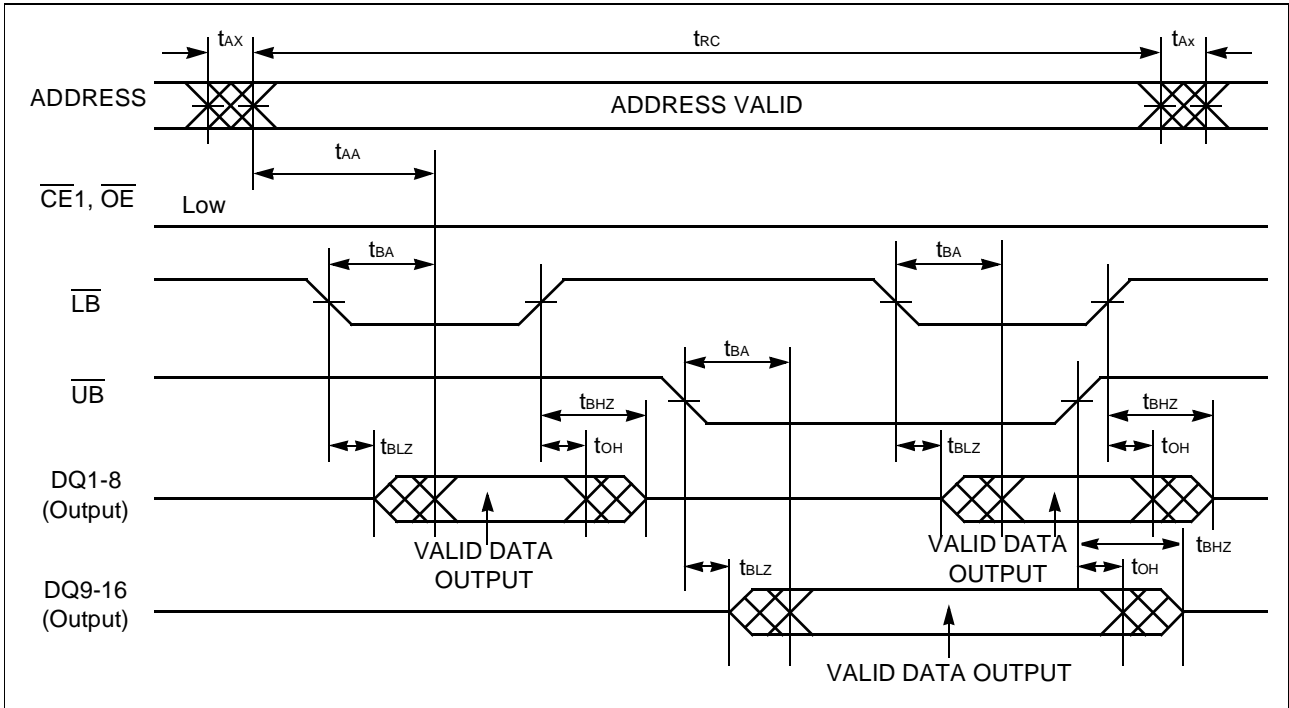


**Notes:** This timing diagram assumes  $CE2=H$  and  $\overline{WE}=H$ .

## ■ TIMING DIAGRAMS (Continued)

READ Timing #3 ( $\overline{\text{LB}}$  /  $\overline{\text{UB}}$  Byte Access)

See Note.

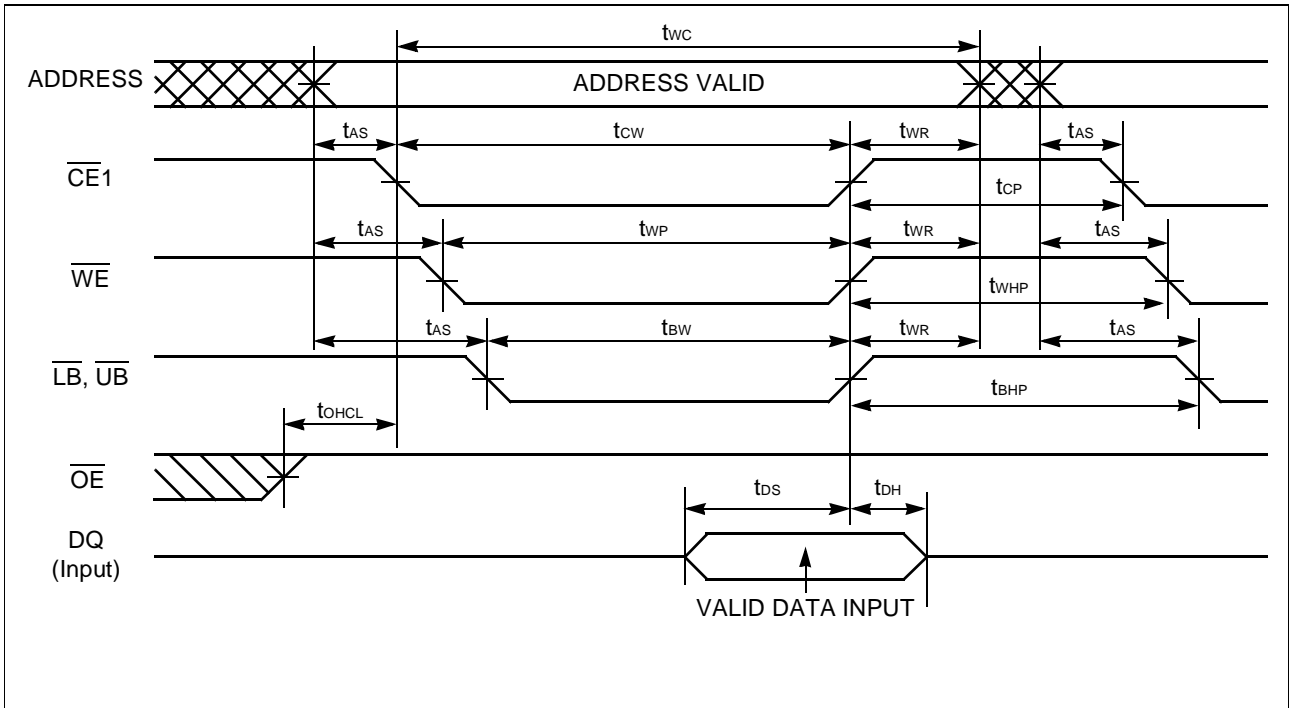


**Note:** This timing diagram assumes  $\text{CE2}=\text{H}$  and  $\overline{\text{WE}}=\text{H}$ .

■ TIMING DIAGRAMS (Continued)

WRITE Timing #1 (Basic Timing)

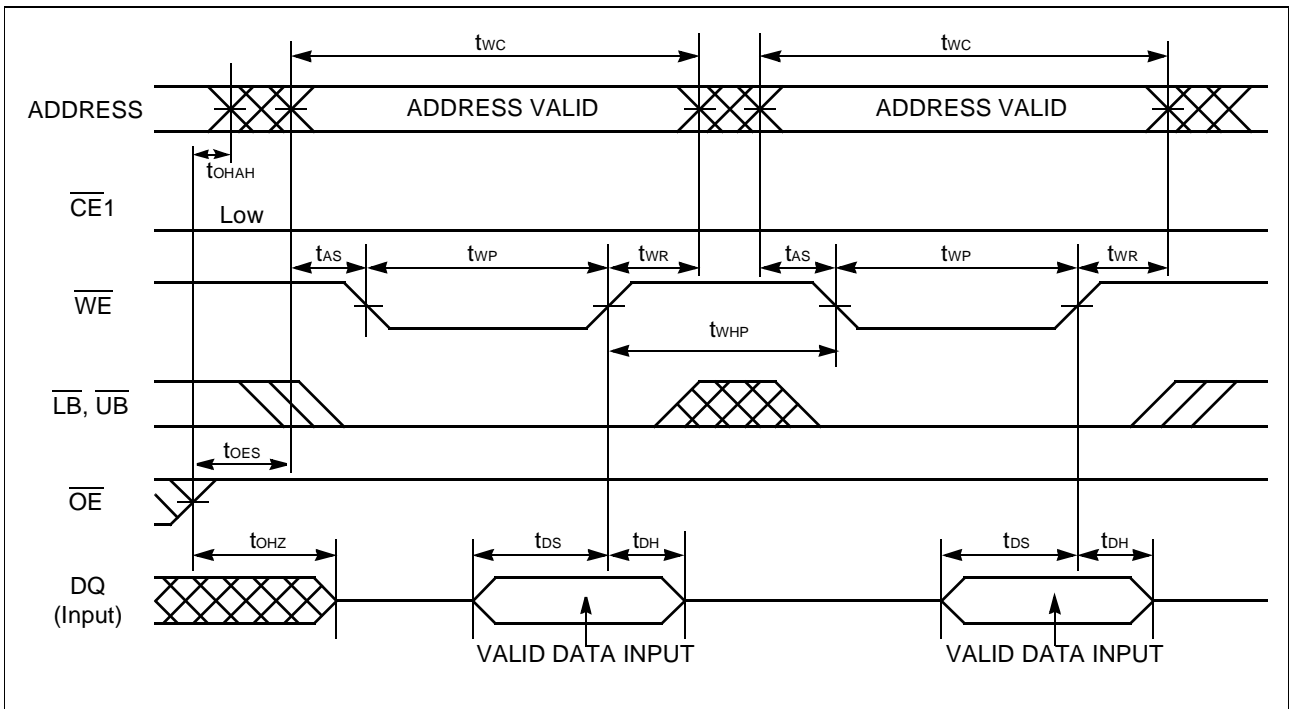
See Note.



Notes: This timing diagram assumes  $CE2=H$ .

WRITE Timing #2 ( $\overline{WE}$  Control)

See Note.

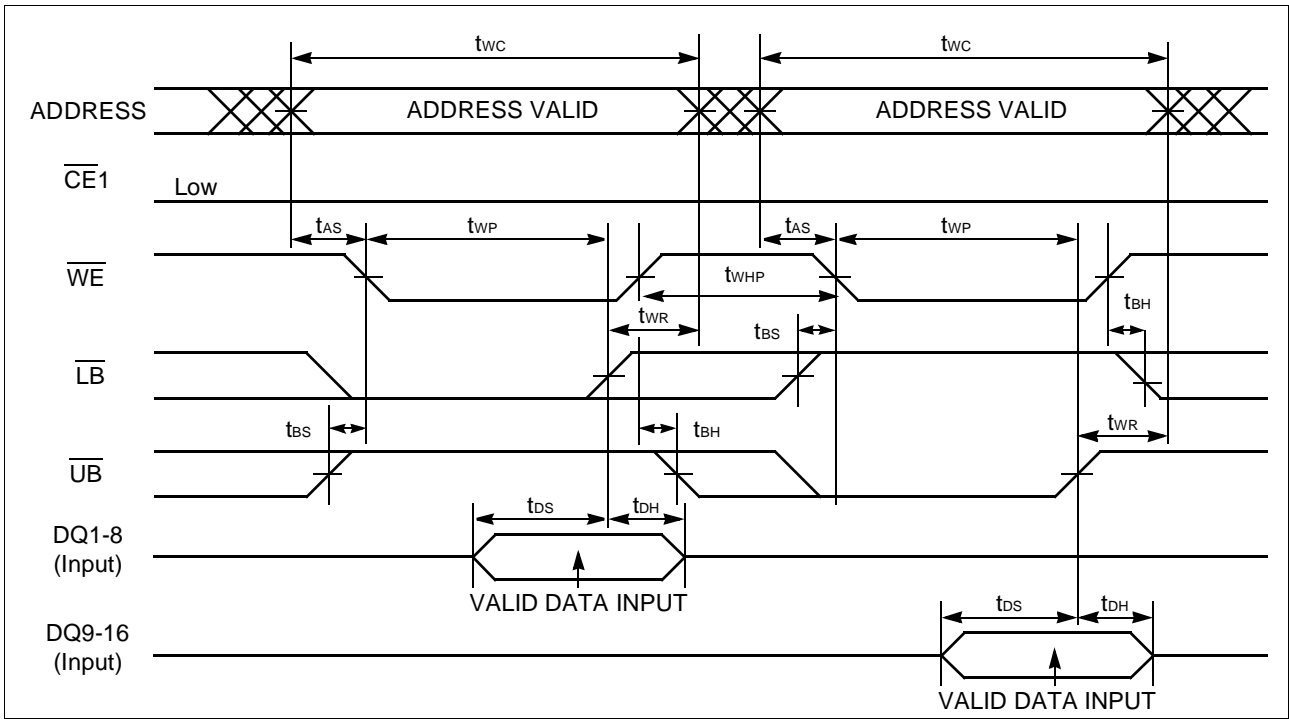


Note: This timing diagram assumes  $CE2=H$ .

## ■ TIMING DIAGRAMS (Continued)

### WRITE Timing #3-1 ( $\overline{WE}$ / $\overline{LB}$ / $\overline{UB}$ Byte Write Control)

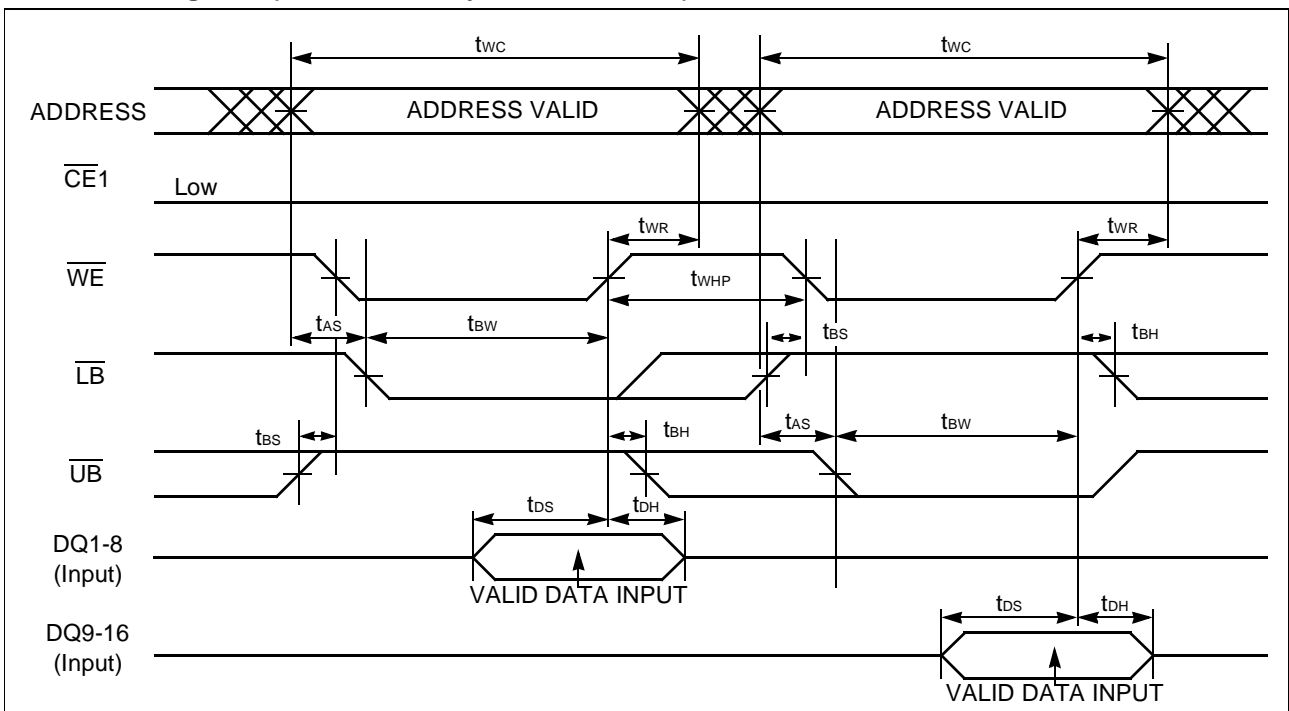
See Note.



**Note:** This timing diagram assumes  $CE2=H$  and  $\overline{OE}=H$ .

### WRITE Timing #3-2 ( $\overline{WE}$ / $\overline{LB}$ / $\overline{UB}$ Byte Write Control)

See Note.

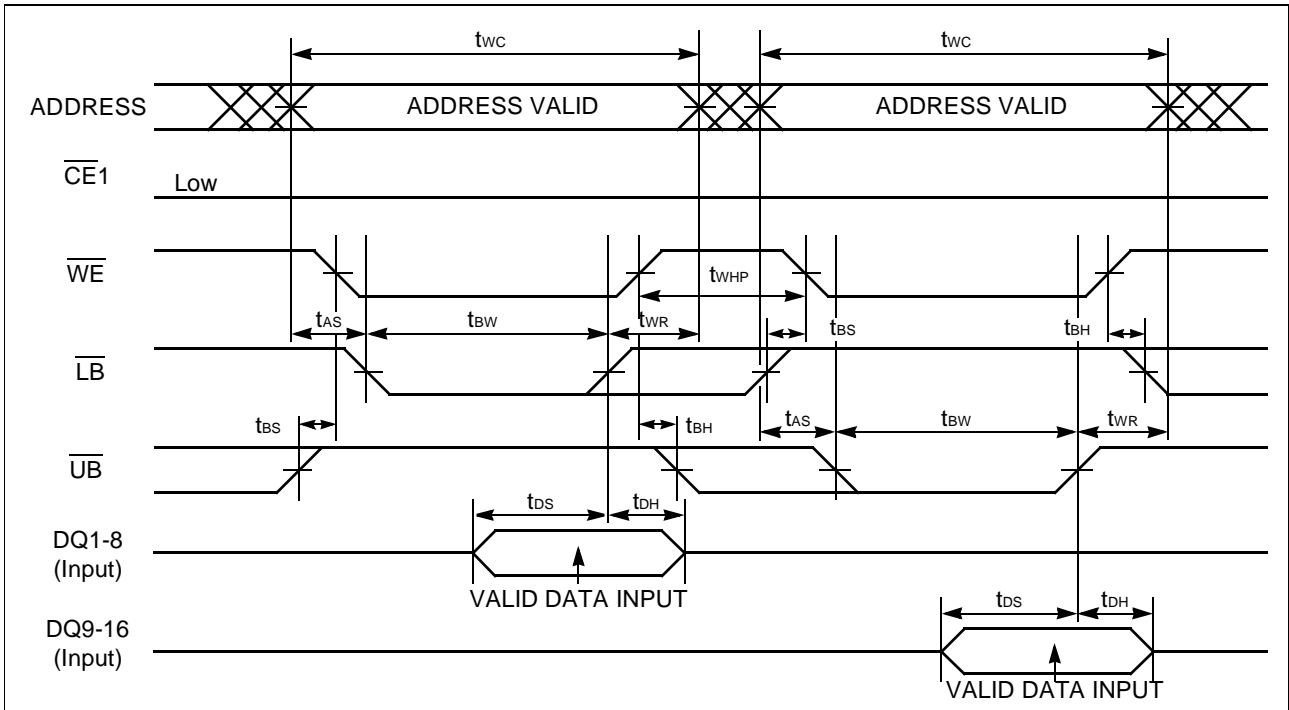


**Note:** This timing diagram assumes  $CE2=H$  and  $\overline{OE}=H$ .

■ TIMING DIAGRAMS (Continued)

WRITE Timing #3-3 ( $\overline{WE}$  /  $\overline{LB}$  /  $\overline{UB}$  Byte Write Control)

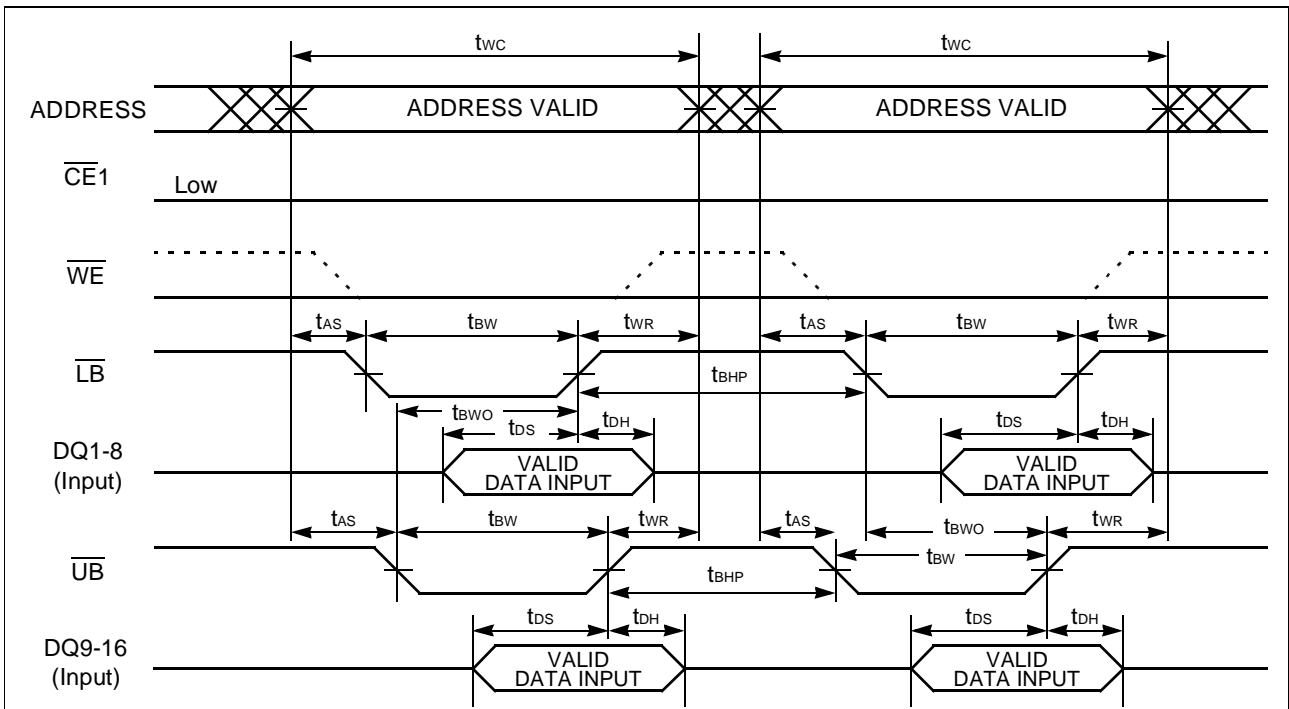
See Note.



Note: This timing diagram assumes  $CE2=H$  and  $\overline{OE}=H$ .

WRITE Timing #3-4 ( $\overline{WE}$  /  $\overline{LB}$  /  $\overline{UB}$  Byte Write Control)

See Note.

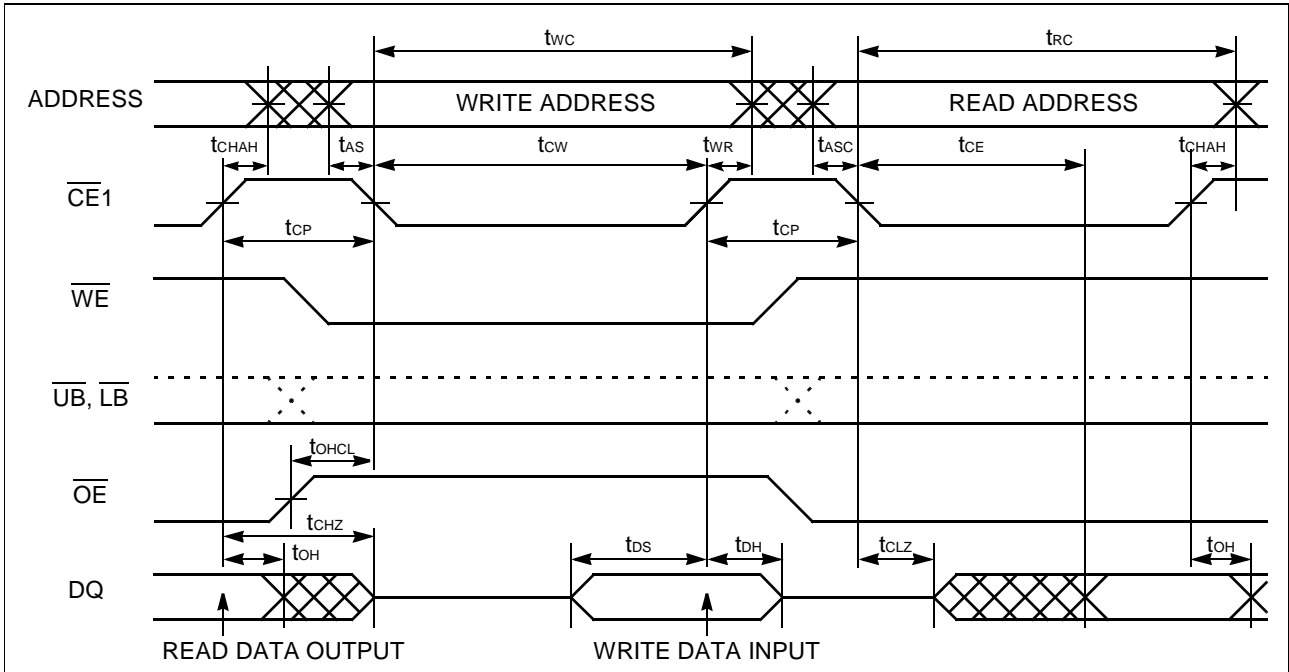


Note: This timing diagram assumes  $CE2=H$  and  $\overline{OE}=H$ .

## ■ TIMING DIAGRAMS (Continued)

### READ / WRITE Timing #1-1 ( $\overline{CE1}$ Control)

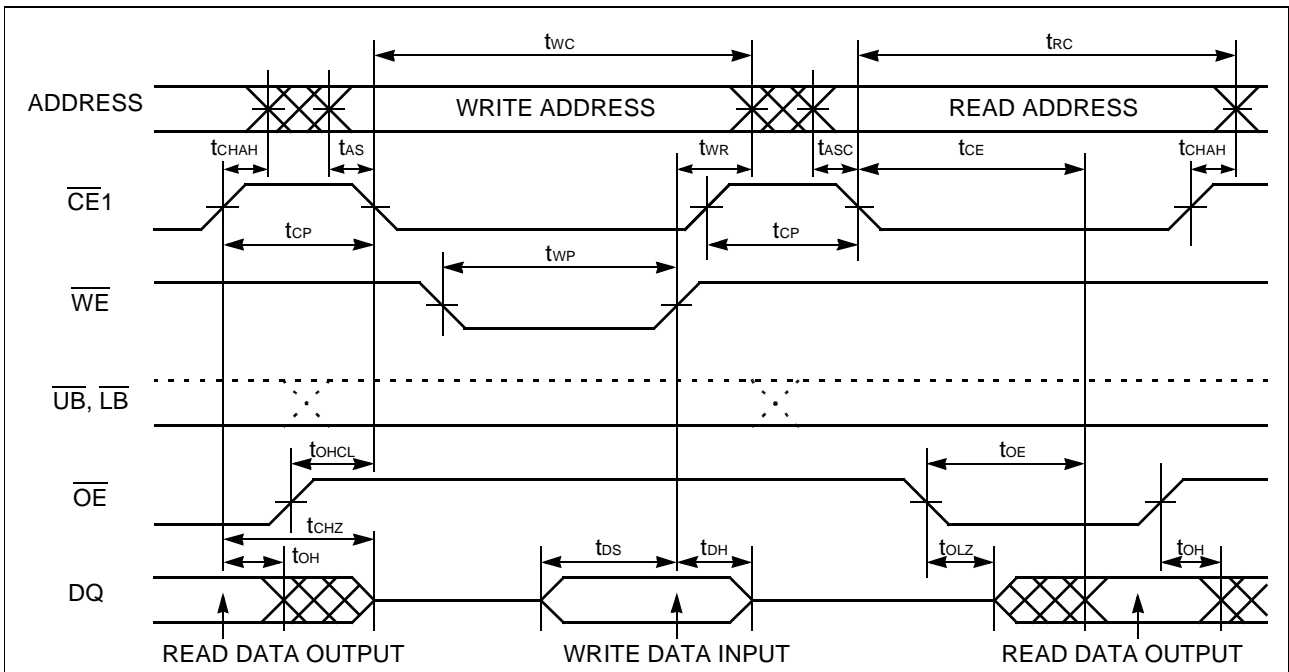
See Note.



- Notes**
- \*1: This timing diagram assumes  $CE2=H$ .
  - \*2: Write address is valid from either  $\overline{CE1}$  or  $\overline{WE}$  of last falling edge.

### READ / WRITE Timing #1-2 ( $\overline{CE1}$ / $\overline{WE}$ / $\overline{OE}$ Control)

See Note.

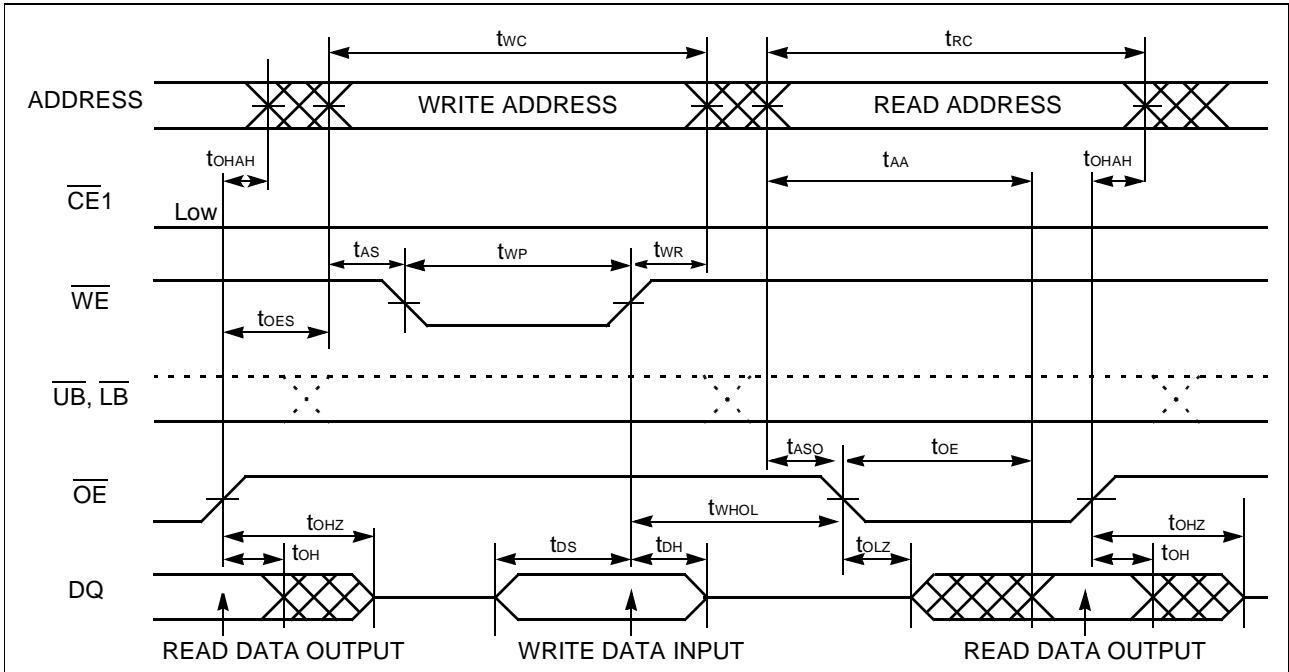


- Notes**
- \*1: This timing diagram assumes  $CE2=H$ .
  - \*2:  $\overline{OE}$  can be fixed Low during write operation if it is  $\overline{CE1}$  controlled write at Read-Write-Read sequence.

■ TIMING DIAGRAMS (Continued)

READ / WRITE Timing #2 ( $\overline{OE}$ ,  $\overline{WE}$  Control)

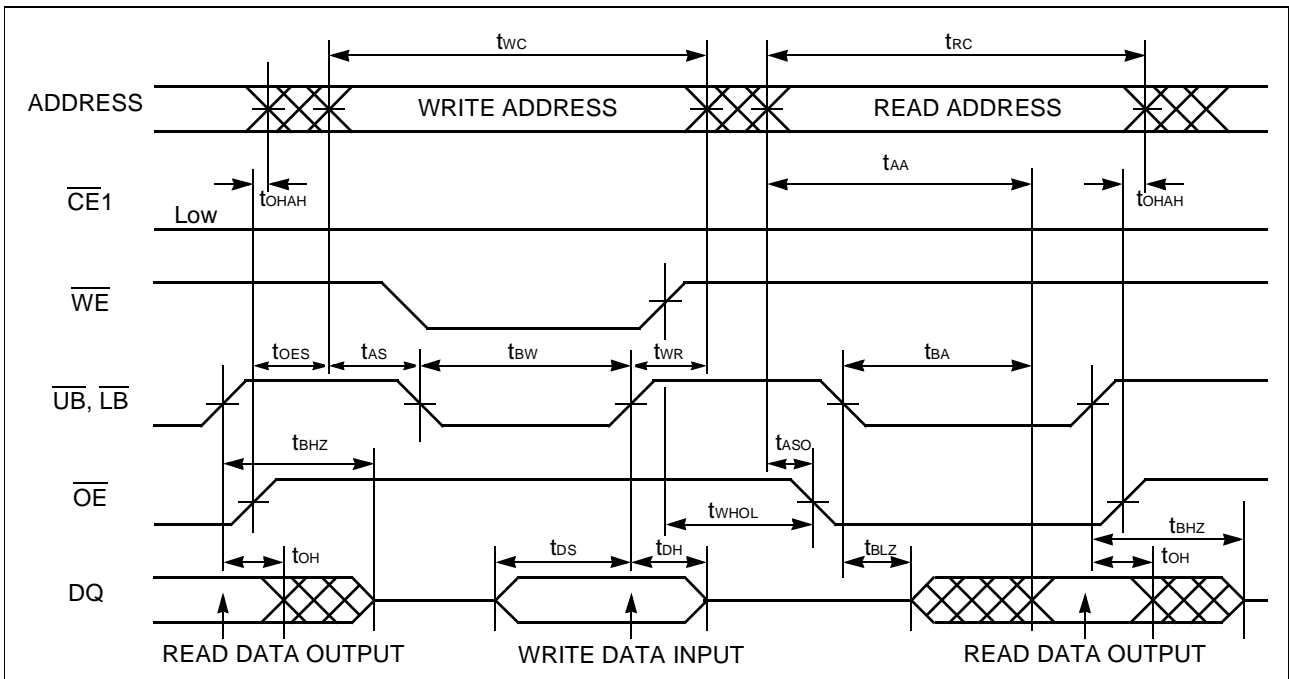
See Note.



- Notes \*1: This timing diagram assumes  $\overline{CE2}=H$ .
- \*2:  $\overline{CE1}$  can be tied to Low for  $\overline{WE}$  and  $\overline{OE}$  controlled operation.

READ / WRITE Timing #3 ( $\overline{OE}$ ,  $\overline{WE}$ ,  $\overline{LB}$ ,  $\overline{UB}$  Control)

See Note.

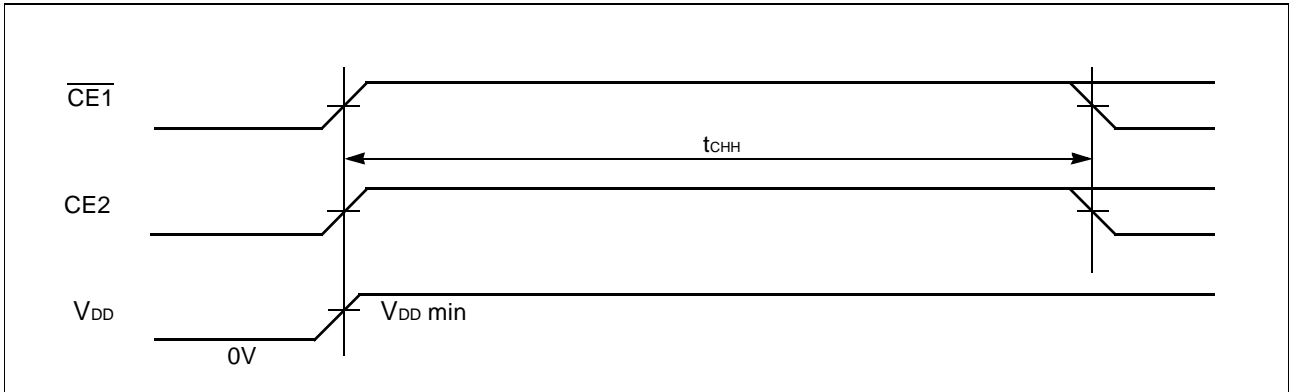


- Notes \*1: This timing diagram assumes  $\overline{CE2}=H$ .
- \*2:  $\overline{CE1}$  can be tied to Low for  $\overline{WE}$  and  $\overline{OE}$  controlled operation.

## ■ TIMING DIAGRAMS (Continued)

### POWER-UP Timing

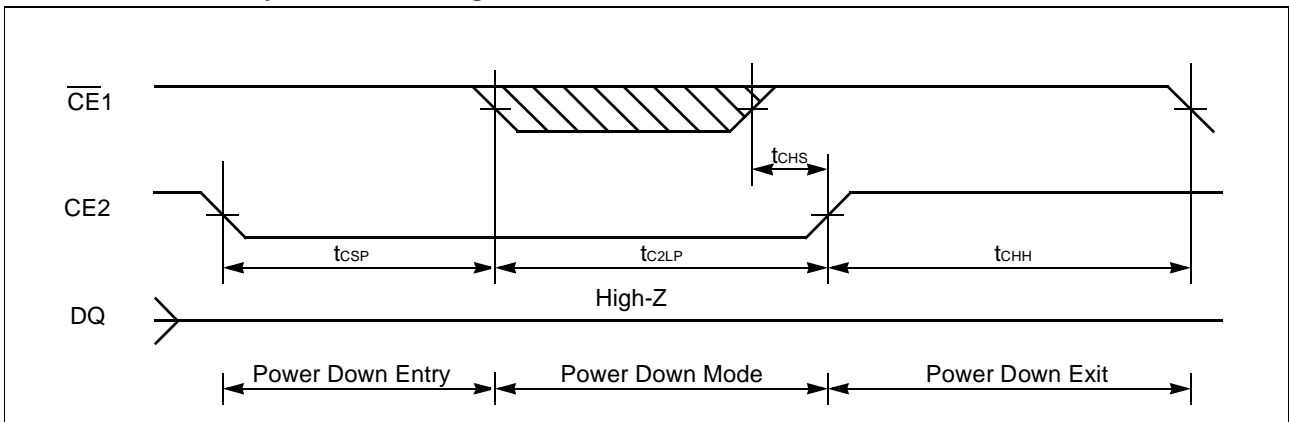
See Note.



**Note:** The  $t_{CHH}$  specifies after  $V_{DD}$  reaches specified minimum level and applicable both  $\overline{CE1}$  and CE2.

### POWER DOWN Entry and Exit Timing

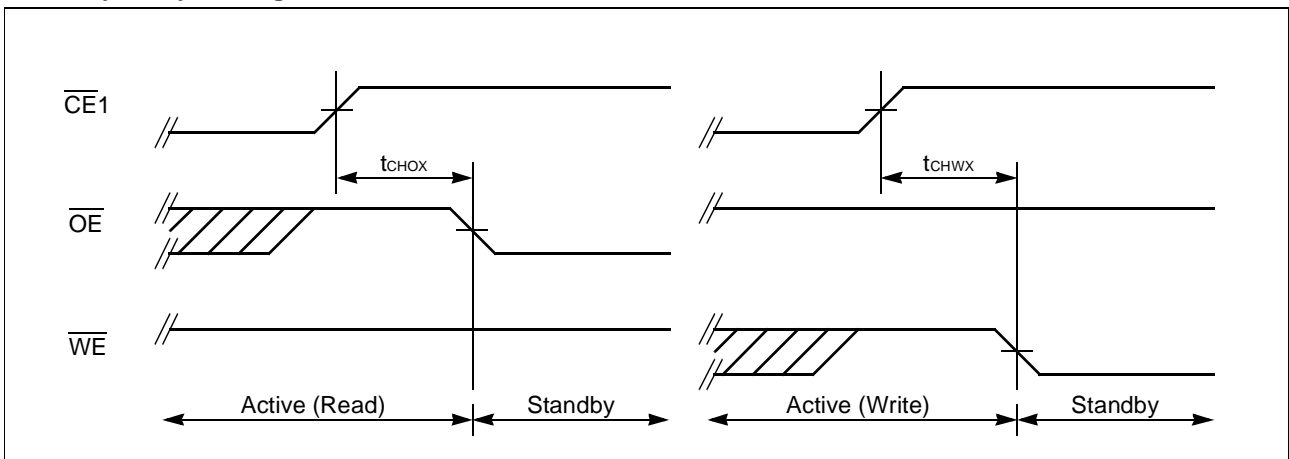
See Note.



**Note:** This Power Down mode can be also used as a reset timing if POWER-UP timing above could not be satisfied and Power-Down program was not performed prior to this reset.

### Standby Entry Timing after Read or Write

See Note.



**Note:** Both  $t_{CHOX}$  and  $t_{CHWX}$  define the earliest entry timing for Standby mode.  
If either of timing is not satisfied, it takes  $t_{RC}$  (min) period for Standby mode from  $\overline{CE1}$  Low to High transition.

**■ BONDING PAD****Bonding Pad Layout**

Please contact local FUJITSU representative for pad layout and pad coordinate information.

**Bonding Pad Description**

<b>Pin Name</b>	<b>Description</b>
A <sub>19</sub> to A <sub>0</sub>	Address Input
$\overline{\text{CE1}}$	Chip Enable (Low Active)
CE2	Chip Enable (High Active)
$\overline{\text{WE}}$	Write Enable (Low Active)
$\overline{\text{OE}}$	Output Enable (Low Active)
$\overline{\text{UB}}$	Upper Byte Control (Low Active)
$\overline{\text{LB}}$	Lower Byte Control (Low Active)
DQ <sub>16-9</sub>	Upper Byte Data Input/Output
DQ <sub>8-1</sub>	Lower Byte Data Input/Output
V <sub>DD</sub>	Power Supply
V <sub>SS</sub>	Ground
TEST/OPEN	Test/Open (This pad should be left open. Do not use.)

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